

Overview

HP ProBook 640 G8 Notebook PC



Left

1. Internal Microphones (2)
2. Webcam LED (Optional)
3. HD Camera (Optional)
4. IR Camera LEDs (Optional)
5. Clickpad
6. Smartcard Reader (Optional)
7. SuperSpeed USB Type-A 5Gbps signaling rate Port
8. RJ-45
9. Nano Security Lock Slot (Lock sold separately)

Overview



Right

1. Power Button Key
2. Power Connector
3. SuperSpeed USB Type-C® 10Gbps signaling rate Port
4. SuperSpeed USB Type-A 5Gbps signaling rate Port
5. SuperSpeed USB Type-A 5Gbps signaling rate Port
6. HDMI Port (Cable not included)
7. Audio Combo Jack
8. SIM Card Slot (Optional)
9. Touch Fingerprint Sensor (select models)

Overview

At a Glance

- New mechanical design - Smaller footprint and Light weight
- Powerful quad core 11th Gen Intel® Core™ U-Series with SIPP CPU option
- NVidia® GeForce MX450 graphics solution (Optional)
- HP Sure View Gen3 panel
- Physical HP Privacy Camera (Optional)
- Gigabit class 4G LTE wireless broadband (Optional)
- HP Fast Charge - Charge up to 50% in 30 minutes
- Wi-Fi 6 capability (Optional)
- Multi Factor Authentication - IR camera Hardened fingerprint sensor (Optional)
- Rich IO ports with charging USB
- Responsiveness w/Modern Standby and Wake on Fingerprint Sensor (Optional)
- Backlit keyboard option and new programmable key
- Nice range of display option from HD, FHD, all the way to SureView option
- Passed 19 MIL STD 810H tests¹

1. MIL-STD 810H is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Technical Specifications

PRODUCT NAME

HP ProBook 640 G8 Notebook PC

OPERATING SYSTEMS

Preinstalled

Windows 10 Pro 64 – HP recommends Windows 10 Pro¹
Windows 10 Pro 64 (National Academic only)²
Windows 10 Home 64¹
Windows 10 Home Single Language 64¹
Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)¹
FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see <https://aka.ms/ProEducation> for Windows 10 Pro Education feature information.

PROCESSORS

Intel® Core™ i7-1185G7 processor (Up to 4.8 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores)^{3,4,5,6}
Intel® Core™ i7-1165G7 processor (Up to 4.7 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores)^{3,4,5,6}
Intel® Core™ i5-1145G7 processor (Up to 4.4 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}
Intel® Core™ i5-1135G7 processor (Up to 4.2 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}
Intel® Core™ i3-1125G4 processor with Intel® UHD Graphics (Up to 3.7 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}
Intel® Core™ i3-1115G4 processor with Intel® UHD Graphics (Up to 4.1 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 2 cores)^{3,4,5,6}

Processors Family

11th Generation Intel® Core™ i7 processor (i7-1165G7 & i7-1185G7)⁷
11th Generation Intel® Core™ i5 processor (i5-1135G7 & i5-1145G7)⁷
11th Generation Intel® Core™ i3 processor (i3-1115G4 & i3-1125G4)⁷

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See <http://www.intel.com/technology/turboboost> for more information.

6. Max Boost clock frequency performance varies depending on hardware, software and overall system configuration.

7. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.



Technical Specifications

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® Iris® Xe Graphics (Core i5 and Core i7)⁴³

Intel® UHD Graphics (Core i3)⁷

Discrete

NVIDIA® GeForce® MX450 (2 GB DDR5 dedicated)

Supports

Support HD decode, DX12, HDMI 1.4b

8. HD content required to view HD images.

43. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.

DISPLAYS

Internal

Non-Touch

35.56 cm (14") diagonal HD SVA eDP anti-glare narrow bezel bent, 250 nits, 45% NTSC(1366 x 768) ^{8,10}

35.56 cm (14") diagonal HD SVA eDP anti-glare narrow bezel bent, 250 nits, 45% NTSC for HD camera (1366 x 768) ^{8,10}

35.56 cm (14") diagonal FHD UWVA eDP anti-glare narrow bezel bent, 250 nits, 45% NTSC (1920 x 1080) ^{8,10}

35.56 cm (14") diagonal FHD UWVA eDP anti-glare narrow bezel bent, 250 nits, 45% NTSC for HD camera (1920 x 1080) ^{8,10}

35.56 cm (14") diagonal FHD UWVA eDP anti-glare narrow bezel bent, 250 nits, 45% NTSC for HD camera and WWAN (1920 x 1080) ^{8,10}

35.56 cm (14") diagonal FHD UWVA eDP anti-glare narrow bezel bent, 250 nits, 45% NTSC for HD + IR camera and WWAN (1920 x 1080) ^{8,10}

35.56 cm (14") diagonal FHD UWVA eDP anti-glare Low Power narrow bezel bent, 400 nits, 72% NTSC for HD camera (1920 x 1080) ^{8,10}

35.56 cm (14") diagonal FHD UWVA eDP anti-glare Low Power narrow bezel bent, 400 nits, 72% NTSC for HD + IR camera and WWAN (1920 x 1080) ^{8,10}

35.56cm (14") diagonal FHD IPS eDP anti-glare flat with HP Sure View Gen3 Integrated Privacy Screen, 1000 nits, 72% NTSC for HD+IR camera and WWAN (1920 x 1080) ^{8,10,11,46}

Touch

35.56 cm (14") diagonal FHD SVA eDP narrow bezel bent touch-on-panel screen, 250 nits, 45% NTSC for HD camera (1920 x 1080) ^{8, 9, 10,46}

35.56 cm (14") diagonal FHD SVA eDP narrow bezel bent touch-on-panel screen, 250 nits, 45% NTSC for HD + IR camera and WWAN (1920 x 1080) ^{8, 9, 10,46}

HDMI

Supports resolutions up to 4K 30Hz



Technical Specifications

- 8. HD content required to view HD images.
- 9. Sold separately or as an optional feature.
- 10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 11. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation. Actual brightness will be lower with touchscreen or Sure View.
- 46. Actual brightness will be lower with HP Sure View or touch screen.

Docking station model	Total number of supported displays (incl. the notebook display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock G2	3	Dual 4K @ 60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	System only runs at alt-mode speed
HP Elite USB-C Dock G5	3	Three 1680x1050 @ 60 Hz Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock G2	3	Dual 4K @ 60Hz Single 5K @ 60Hz	1xHDMI, 2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time



Technical Specifications

STORAGE AND DRIVES

Primary M.2 Storage

- 128 GB PCIe® NVMe™ M.2 TLC Solid State Drive¹²
- 256 GB PCIe® NVMe™ M.2 Value Solid State Drive¹²
- 256 GB PCIe® NVMe™ M.2 TLC Solid State Drive¹²
- 256 GB PCIe® NVMe™ M.2 TLC Solid State Drive (Opal 2)¹²
- 512 GB PCIe® NVMe™ M.2 TLC Solid State Drive¹²
- 512 GB PCIe® NVMe™ M.2 Value Solid State Drive¹²
- 512 GB PCIe® Gen3x4 NVMe™ M.2 SED SSD TLC¹²
- 512 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 32 GB Intel® Optane™ memory H10^{12,45}
- 1 TB PCIe® NVMe™ M.2 TLC Solid State Drive¹²

12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

45. Intel® Optane™ H10 memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.

MEMORY⁴⁴

Maximum Memory

64 GB DDR4-3200 SDRAM¹³

Memory

- 64 GB DDR4-3200 SDRAM (2 x 32 GB)¹³
- 32 GB DDR4-3200 SDRAM (1 x 32 GB)¹³
- 32 GB DDR4-3200 SDRAM (2 x 16 GB)¹³
- 16 GB DDR4-3200 SDRAM (1 x 16 GB)¹³
- 16 GB DDR4-3200 SDRAM (2 x 8 GB)¹³
- 12 GB DDR4- 3200 SDRAM (4 GB and 8 GB (1 x 8 GB)¹³
- 8 GB DDR4-3200 SDRAM (1 x 8 GB)¹³
- 8 GB DDR4-3200 SDRAM (2 x 4 GB)¹³
- 4 GB DDR4-3200 SDRAM (1 x 4 GB)¹³

Memory Slots

2 SODIMM

Both slots are customer accessible / upgradeable

DDR4 PC4 SODIMMS, (Tiger Lake runs at 3200)

Supports Dual Channel Memory

13. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

44. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.



Technical Specifications

NETWORKING/COMMUNICATIONS

WLAN

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, vPro, supporting gigabit file transfer speeds)¹⁴

Intel® Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 5 Combo, non-vPro[®]™¹⁴

Intel® Dual Band Wi-Fi 6 AX201 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 5 Combo, non-vPro[®]™¹⁴

WWAN

Intel® XMM™ 7360 LTE-Advanced (Cat9)¹⁵

NFC

NFC Mirage WNC XRAV-1

Ethernet

Intel 10/100/1000 NIC¹⁶

14. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

15. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

16. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA

Audio

2 Integrated stereo speakers (70dB)

Integrated microphone (Dual Array)

Camera

720p HD Camera⁸

720p HD Camera+IR Camera^{8,9}

8. HD content required to view HD images.

9. Sold separately or as an optional feature.



Technical Specifications

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with optional backlit function

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

F1 - Display Switching

F2 - Blank or SureView On/Off

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - Insert

F11 - Airplane mode

F12 - Programmable key

Hidden Function Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

SOFTWARE AND SECURITY

Preinstalled Software

HP BIOSphere Gen5 ¹⁷

NVMe Driverlock

BIOS Update (Status) Over Wi-fi

Power On Authentication

HP Secure Erase ¹⁹

Absolute Persistence Module ²⁰

HP LAN-Wireless Protection

Pre-Boot Security

Software

HP Connection Optimizer ¹⁸

HP Image Assistant

HP Hotkey Support

myHP

HP Support Assistant ²¹

HP Noise Cancellation Software

HSA Fusion for Commercial

HSA Telemetry for Commercial

Touchpoint Customizer for Commercial



Technical Specifications

HP Notifications
HP Privacy Settings
HP Wireless Button Driver
HP Power Manager
HP Smart Support ⁴⁸

Manageability Features

HP Driver Packs (download) ²²
HP Manageability Integration Kit Gen3 (download) ²³
HP System Software Manager (SSM) (download)
HP BIOS Config Utility (BCU) (download)
HP Client Catalog (download)
HP Client Management Script Library (download)

Client Security Software

HP Client Security Manager Gen7 ²⁴
Windows Defender ²⁵

Security Management

Pre-boot Security
USB enable/disable (via BIOS)
Power-on password (via BIOS)
Setup password (via BIOS)
HP Fingerprint Sensor ²⁶
Support for chassis padlocks and cable lock devices
HP Pro Security Edition (Select models) ⁴³
HP Sure Click ²⁷
HP Sure Sense ²⁸
HP Sure Start Gen6 ²⁹
HP Sure Admin ³⁰
HP Sure Recover Gen4 ³¹
HP Sure Run Gen4 ³²
TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified) ³³

Security

TPM

Model: Infineon SLB9670
Version: 7.85
Revision: TPM 2.0
FIPS 140-2 Compliant: Yes

Smartcard Reader

Model number: Alcor AU9560
FIPS 201 Compliant: Yes

IPv6 Compliance

Yes

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?: Yes

UEFI version: 2.7



Technical Specifications

17. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
18. HP Connection Optimizer requires Windows 10.
19. HP Secure Erase For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
20. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: <https://www.absolute.com/about/legal/agreements/absolute/>.
21. HP Support Assistant requires Windows and Internet access.
22. HP Driver Packs not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>.
23. HP Manageability Integration Kit can be downloaded from <http://www.hp.com/go/clientmanagement>.
24. HP Client Security Manager Gen6 requires Windows and is available on the select HP Pro and Elite PCs.
25. Windows Defender Opt in and internet connection required for updates.
26. HP Fingerprint sensor is an optional feature that must be configured at purchase.
27. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
28. HP Sure Sense requires Windows 10.
29. HP Sure Start Gen6 is available on select HP PCs.
30. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from <http://www.hp.com/go/clientmanagement> and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
31. HP Sure Recover Gen3 is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.
32. HP Sure Run Gen3 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors.
33. Firmware TPM is version 2.0.
43. HP Pro Security Edition is available preloaded on select HP PCs and includes HP Sure Click Pro and HP Sure Sense Pro. 3-year license required. The HP Pro Security Edition software is licensed under the license terms of the HP End User License Agreement (EULA) that can be found at: https://h30670.www3.hp.com/ecommerce/common/disclaimer.do#EN_US as modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for thirty-six (36) months thereafter ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support." HP Pro Security Edition is optimized for the SMB environment and ships pre-configured - manageability is optional. The HP Pro Security Edition supports a limited tool set that can be used by the HP Manageability Integration Kit which can be downloaded from <http://www.hp.com/go/clientmanagement>.
48. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: <http://www.hp.com/smart-support>. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.



Technical Specifications

POWER

Power Supply¹⁶

HP Smart 65 W External AC power adapter ³⁴
HP Smart 65 W EM External AC power adapter ³⁴
HP Smart 65 W USB Type-C® adapter ³⁴
HP Smart 45 W External AC power adapter ³⁴
HP Smart 45 W USB Type-C® adapter ³⁴

Primary Battery

HP Long Life 3-cell, 45 Wh Polymer ³⁵

Power Cord

3-wire plug - 1m ³⁴
2-wire plug - 1m ³⁴

Battery life

MM18: Up to 12 hours and 45 minutes

Battery Weight

190 g

[34. Availability may vary by country.](#)

[35. Battery is internal and not replaceable by customer. Serviceable by warranty.](#)

WEIGHTS & DIMENSIONS

Product Weight³⁶

Starting at 3.03 lb
Starting at 1.38 kg (400 nits display only)

Product Dimensions (w x d x h)

12.67 x 8.42 x 0.78 in
32.19 x 21.39 x 1.99 cm

[36. Weight will vary by configuration.](#)

Technical Specifications

PORTS/SLOTS

Ports

- 1 HDMI 1.4b ³⁷
- 1 Headphone/microphone combo jack
- 1 AC power
- 1 Nano SIM (optional)
- 1 RJ-45

USB Ports

Processor Type	Type-C® Port	Type-A Port
Transactional + Thunderbolt version (non-vPro®)	1 Thunderbolt™ 4 with USB4™ Type-C® 40 Gbps signaling rate (USB Power Delivery, DisplayPort™) ⁴⁷	2 SuperSpeed USB Type-A 5Gbps signaling rate Port (1 Powered port) 1 SuperSpeed USB Type-A 5Gbps signaling rate Port (Power delivery)
vPro®	1 Thunderbolt™ 4 with USB4™ Type-C® 40 Gbps signaling rate (USB Power Delivery, DisplayPort™) ⁴⁷	2 SuperSpeed USB Type-A 5Gbps signaling rate Port (1 Powered port) 1 SuperSpeed USB Type-A 5Gbps signaling rate Port (Power delivery)

Expansion Slots

- 1 Smart Card Reader (optional)

[37. HDMI cable sold separately.](#)

[47. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.](#)

Technical Specifications

SERVICE AND SUPPORT

HP Services offers 1-year and 3-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one-year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to <http://www.hp.com/support/batterywarranty/> for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.³⁸

38. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <http://www.hp.com/go/cpc>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance	ENERGY STAR® certified
Energy Efficiency Compliance	EPEAT® 2019 Silver ³⁹
Environmental Specifications	Low halogen ⁴⁰
Environmental Specifications	TCO NB 8.0 Certification

39. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit <http://www.epeat.net> for more information.

40. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)

Nominal Operating Voltage	19 V
Average Operating Power	4.62 W
Integrated graphics	Yes
Discrete Graphics	N185-G5: 25W
Max Operating Power	Discrete < 65W UMA < 45W

Temperature

Operating	32° to 95° F (0° to 35° C)
Non-operating	-4° to 140° F (-20° to 60° C)

Relative Humidity

Operating	10% to 90%, non-condensing
Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock

Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine

Random Vibration

Operating	0.75 grms
Non-operating	1.50 grms

Altitude (unpressurized)

Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard Certifications

UL	Yes
CSA	Yes
FCC Compliance	Yes
ENERGY STAR®	Select models ⁴¹
EPEAT®	EPEAT® 2019 Gold in U.S. ⁴²
ICES	Yes
Australia /	Yes
NZ A – Tick Compliance	Yes
CCC	Yes
Japan VCCI Compliance	Yes
KC	Yes
BSMI	Yes
CE Marketing Compliance	Yes
BNCI or BELUS	Yes
CIT	Yes
GOST	Yes
Saudi Arabian Compliance (ICCP)	Yes
SABS	Yes



Technical Specifications

41. Configurations of the HP ProBook 640 G8 that are ENERGY STAR® certified are identified as HP ProBook 640 G8 ENERGY STAR on HP websites and on <http://www.energystar.gov>.

42. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit <http://www.epeat.net> for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

1. Actual brightness will be lower with HP Sure View or touch screen.

Panel LCD 14 inch FHD (1920x1080) Anti-Glare WLED UWVA 45% NTSC 250 nits eDP 1.2 w/o PSR bent NWBZ	Outline Dimensions (W x H x D)	316.17 x 186.4 mm (max) (w/ PCB)
	Active Area	309.37 x 174.02 mm (typ.)
	Weight	300 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm/ 5.0 mm (PCB) (max)
	Interface	eDP 1.2
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format	RGB Stripe
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits (Hi FRC supportive w/ condition to enable)
	Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch FHD (1920x1080) Anti-Glare WLED UWVA 45% NTSC 250 nits eDP 1.2 w/o PSR bent Touch on Panel NWBZ	Outline Dimensions (W x H x D)	316.17 x 186.4 mm (max) (w/ PCB)
	Active Area	309.37 x 174.02 mm (typ.)
	Weight	305 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm/ 5.0 mm (PCB) (max)
	Interface	eDP 1.2
	Surface Treatment	Anti-Glare On-cell
	Touch Enabled	Yes
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness¹	250 nits*
	Pixel Resolution	1920 x 1080 (FHD)



Technical Specifications

Format	RGB Stripe
Backlight	LED
Color Gamut Coverage	45% of NTSC
Color Depth	6 bits (Hi FRC supportive w/ condition to enable)
Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch FHD (1920x1080) Anti-Glare WLED UWVA 72 percent cg 1000nits eDP 1.4+PSR2 bent Privacy NB2X Gen3

Outline Dimensions (W x H x D)	315.31 x 186.48mm (max.)
Active Area	309.31 x 173.99
Weight	220g max.
Diagonal Size	14 (inch)
Thickness	3.9 mm max.
Interface	eDP 1.4 + PSR (4 lane)
Surface Treatment	Anti-Glare (AG)
Touch Enabled	No
Contrast Ratio	2000:1 (typ.)
Refresh Rate	60Hz
Brightness	1000 nits
Pixel Resolution	1920x1080
Format	RGB
Backlight	LED
Color Gamut Coverage	sRGB 100%
Color Depth	8bits
Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch FHD (1920x1080) Anti-Glare WLED UWVA sRGB 100 percent cg 400nits eDP 1.4+PSR2 bent LP NB2X

Outline Dimensions (W x H x D)	315.31 x 186.48 mm (max)
Active Area	309.312 x 173.988 mm (typ.)
Weight	220 g (max)
Diagonal Size	14.0 inch
Thickness	3.9 mm (max)
Interface	eDP 1.4 + PSR (4 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	1200:1 (typ.)
Refresh Rate	60 Hz
Brightness	400 nits
Pixel Resolution	1920 x 1080 (FHD)
Format	RGB
Backlight	LED
Color Gamut Coverage	sRGB 100%
Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85



Technical Specifications

Panel LCD 14-inch HD (1366x768) Anti-Glare WLED SVA 45% NTSC 250 nits eDP 1.2 w/o PSR NWBZ bent	Outline Dimensions (W x H x D)	316.1 x 186.37 (mm) max
	Active Area	309.4 x 173.95 (mm)
	Weight	300g Max
	Diagonal Size	14"
	Thickness	3.2mm / 5.0mm (Panel + PCB) (max)
	Interface	eDP 1.2 (1 lane)
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	300:1 (typ)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1366 x 768 (HD)
	Format	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits
	Viewing Angle	SVA 45/45/15/35

Technical Specifications

STORAGE AND DRIVES¹

1. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software

SSD 128GB 2280 PCIe-3x2 Three Layer Cell	Form Factor	M.2 2280
	Capacity	128 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe
	Maximum Sequential Read	1400 ~ 2100 MB/s
	Maximum Sequential Write	800 ~ 1200 MB/s
	Logical Blocks	250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; DIPM; TRIM; DEVSLP

SSD 1 TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided	Form Factor	M.2 2280
	Capacity	1 TB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3x4
	Maximum Sequential Read	3100 ~ 3500 MB/s
	Maximum Sequential Write	2770 ~ 3037 MB/s
	Logical Blocks	2,000,409,264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2

SSD 256GB 2280 PCIe NVMe Value	Form Factor	M.2 2280
	Capacity	256 GB
	NAND Type	Value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3
	Maximum Sequential Read	2100 ~ 2200 MB/s



Technical Specifications

Maximum Sequential Write	900 ~ 1400 MB/s
Logical Blocks	500,118,192
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security (optional); TRIM; L1.2

SSD 512GB 2280 PCIe NVMe Value	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	Value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3
	Maximum Sequential Read	2200 ~ 2300 MB/s
	Maximum Sequential Write	1000 ~ 1600 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security (optional); TRIM; L1.2	

SSD 512GB 2280 PCIe-3x2x2 NVMe+SSD 32GB 3D Xpoint	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	QLC+3D XPoint
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X2X2
	Maximum Sequential Read	Up to 2400 MB/s
	Maximum Sequential Write	Up to 1300 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2	

SSD 512GB 2280 M2 PCIe-3x4 SS NVMe TLC	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)



 Technical Specifications

Interface	PCIe NVMe Gen3X4
Maximum Sequential Read	3100 ~ 3500 MB/s
Maximum Sequential Write	2400 ~ 2956 MB/s
Logical Blocks	1,000,215,215
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2

SSD 256GB 2280 M2 PCIe-3x4 SS NVMe TLC	Form Factor	M.2 2280
	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	2800 ~ 3500 MB/s
	Maximum Sequential Write	1400 ~ 2200 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2	

SSD 256GB 2280 PCIe-3x4 NVMe Self Encrypted OPAL2 Three Layer Cell	Form Factor	M.2 2280
	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	2800 ~ 3500 MB/s
	Maximum Sequential Write	1663 ~ 2200 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2	

Technical Specifications

SSD 512GB 2280 PCIe-3x4 NVMe Self Encrypted OPAL2 Three Layer	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	3100 ~ 3500 MB/s
	Maximum Sequential Write	2400 ~ 2956 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

Technical Specifications

NETWORKING/COMMUNICATIONS

Intel Wi-Fi 6 AX201 + Bluetooth® 5 (802.11ax 2x2, vPro, supporting gigabit file transfer speeds) ^{5,6}	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Features Wi-Fi 6 technology
	Frequency Band	<ul style="list-style-type: none"> • 802.11b/g/n/ax 2.402 – 2.482 GHz • 802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz) • 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security³	<ul style="list-style-type: none"> • IEEE compliant 64 / 128-bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 certification • IEEE 802.11i • WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum



Technical Specifications

	<ul style="list-style-type: none"> • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum • 802.11ax VHT160(5GHz): +10dBm minimum 				
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW 				
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Sensitivity³	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum • 802.11ax, MCS11(HT40): -59dBm maximum • 802.11ax, MCS11(VHT160): -58.5dBm maximum 				
Antenna type	<p>High efficiency antenna with spatial diversity, mounted in the display enclosure</p> <p>Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications</p>				
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface				
Dimensions	<ol style="list-style-type: none"> 1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm 				
Weight	<ol style="list-style-type: none"> 1. Type 2230: 2.8 g 2. Type 126: 1.3 g 				
Operating Voltage	3.3v +/- 9%				
Temperature	<table border="0"> <tbody> <tr> <td>Operating</td> <td>14° to 158° F (-10° to 70° C)</td> </tr> <tr> <td>Non-operating</td> <td>-40° to 176° F (-40° to 80° C)</td> </tr> </tbody> </table>	Operating	14° to 158° F (-10° to 70° C)	Non-operating	-40° to 176° F (-40° to 80° C)
Operating	14° to 158° F (-10° to 70° C)				
Non-operating	-40° to 176° F (-40° to 80° C)				
Humidity	<table border="0"> <tbody> <tr> <td>Operating</td> <td>10% to 90% (non-condensing)</td> </tr> <tr> <td>Non-operating</td> <td>5% to 95% (non-condensing)</td> </tr> </tbody> </table>	Operating	10% to 90% (non-condensing)	Non-operating	5% to 95% (non-condensing)
Operating	10% to 90% (non-condensing)				
Non-operating	5% to 95% (non-condensing)				
Altitude	<table border="0"> <tbody> <tr> <td>Operating</td> <td>0 to 10,000 ft (3,048 m)</td> </tr> <tr> <td>Non-operating</td> <td>0 to 50,000 ft (15,240 m)</td> </tr> </tbody> </table>	Operating	0 to 10,000 ft (3,048 m)	Non-operating	0 to 50,000 ft (15,240 m)
Operating	0 to 10,000 ft (3,048 m)				
Non-operating	0 to 50,000 ft (15,240 m)				



Technical Specifications

LED Activity	LED Amber – Radio OFF LED Off – Radio ON
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HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP) ² Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)



Technical Specifications

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.
2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
5. Wi-Fi supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160MHz channels.
6. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

Intel Wi-Fi 6 AX201 + Bluetooth® 5 (802.11ax 2x2, non-vPro, supporting gigabit file transfer speeds) ^{5,6} Non-vPro	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Features Wi-Fi 6 technology
	Frequency Band	<ul style="list-style-type: none"> • 802.11b/g/n/ax 2.402 – 2.482 GHz • 802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz) • 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM



Technical Specifications

Security³	<ul style="list-style-type: none"> • IEEE compliant 64 / 128-bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum • 802.11ax VHT160(5GHz): +10dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum • 802.11ax, MCS11(HT40): -59dBm maximum • 802.11ax, MCS11(VHT160): -58.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	<ol style="list-style-type: none"> 1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm



Technical Specifications

Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (–10° to 70° C) Non-operating –40° to 176° F (–40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED Off – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
Transmit Power	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan



Technical Specifications

BT4.2 ESR08 Compliance
 LE Secure Connection- Basic/Full
 LE Privacy 1.2 –Link Layer Privacy
 LE Privacy 1.2 –Extended Scanner Filter Policies
 LE Data Packet Length Extension
 FAX Profile (FAX)
 Basic Imaging Profile (BIP)2
 Headset Profile (HSP)
 Hands Free Profile (HFP)
 Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.
2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
5. Wi-Fi supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160MHz channels.
6. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

**Intel Jefferson Peak2
 9560 802.11a/b/g/n/ac
 (2x2) WiFi® and
 Bluetooth® 5.0 Combo¹
 non-vPro**

Wireless LAN Standards

IEEE 802.11a
 IEEE 802.11b
 IEEE 802.11g
 IEEE 802.11n
 IEEE 802.11ac
 IEEE 802.11d
 IEEE 802.11e
 IEEE 802.11h
 IEEE 802.11i
 IEEE 802.11k
 IEEE 802.11r
 IEEE 802.11v

Interoperability

Wi-Fi® CERTIFIED modules

Frequency Band

- 802.11b/g/n
2.402 – 2.482 GHz
- 802.11a/n/ac
4.9 – 4.95 GHz (Japan)
5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz
5.825 – 5.850 GHz

Data Rates

- 802.11b: 1, 2, 5.5, 11 Mbps



Technical Specifications

	<ul style="list-style-type: none"> • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security³	<ul style="list-style-type: none"> • IEEE and WiFi compliant 64 / 128-bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity⁴	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications



Technical Specifications

Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (–10° to 70° C)
	Non-operating	–40° to 176° F (–40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED Off – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ throughput up to 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ throughput up to 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer



Technical Specifications

LE Low Duty Cycle Directed Advertising
 LE L2CAP Connection Oriented Channels
 Train Nudging & Interlaced Scan
 BT4.2 ESR08 Compliance
 LE Secure Connection- Basic/Full
 LE Privacy 1.2 –Link Layer Privacy
 LE Privacy 1.2 –Extended Scanner Filter Policies
 LE Data Packet Length Extension
 FAX Profile (FAX)
 Basic Imaging Profile (BIP)2
 Headset Profile (HSP)
 Hands Free Profile (HFP)
 Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11 ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160 MHz channels.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® XMM™ 7360 LTE-Advanced CAT9	Technology/Operating bands	<p>FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66).</p> <p>TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41).</p> <p>HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz</p>
	Wireless protocol standards	<p>3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification</p>
	GPS	<p>Standalone, A-GPS (MS-A, MS-B)</p>
	GPS bands	<p>1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz</p>
	Maximum data rates	<p>LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)</p>
	Maximum output power	<p>LTE: 23 dBm HSPA+: 23.5 dBm</p>



 Technical Specifications

Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	5.8 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

NXP NPC300 Near Field Communication Module	Dimensions (L x W x H)	Module 17 mm by 10 mm by 2.0 mm
	Chipset	NPC300
	System interface	I2C
	NFC RF standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2
	NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2
	Reader (PCD-VCD) Mode¹	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards 1. With application or UICC support
	Card Emulation (PICC-VICC) Mode¹	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa 1. With application or UICC support
	Frequency	13.56 MHz
	NFC Modes Supported	Reader/Writer, Peer-to-Peer
	Raw RF Data Rates	106, 212, 424, 848 kbps
	Operating temperature	-25°C to 80°C
	Storage temperature	-25°C to 125°C
	Humidity	10-90% operating 5-95% non-operating
	Supply Operating voltage	2.7 to 5.5 Volts
I/O Voltage	1.8V or 3.3V	

Technical Specifications

Power Consumption

(Booster enable, VBAT= 3.3V, VCC_BOOST = 5V)

Mode	Power Consumption, Typical Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence and period configured.
Polling	710.93 mW
Detected Test Tag Type 1	152.09 mW
Detected Test Tag Type 2	341.26 mW
Detected Test Tag Type 3	383.76 mW
Detected Test Tag Type 4	312.26 mW
Antenna	Antenna connector, 0.3mm pitch, 7 connector FPC. Antenna matching is external to module.

Intel i219v 10/100/1000 Integrated NIC	Connector	RJ-45
	System Interface	PCI (Intel proprietary) + SMBus
	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling (Hash Mode Only) Jumbo Frame 9K
	Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Management Interface	Auto MDI/MDIX Crossover cable detection
	IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)



Technical Specifications

PXE 2.1 Remote Boot
 Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
 Comprehensive diagnostic and configuration software suite
 Virtual Cable Doctor for Ethernet cable status

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

Intel® I219-LM 1 Gigabit Network Connection LOM (vPro)	Connector	RJ-45
	System Interface	PCI (Intel proprietary) + SMBus
	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling (Hash Mode Only) Jumbo Frame 9K
	Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Management Interface	Auto MDI/MDIX Crossover cable detection
	IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components



Technical Specifications

Intel® I219-LM 1 Gigabit Network Connection LOM (non-vPro)	Connector	RJ-45
	System Interface	PCI (Intel proprietary) + SMBus
	Data rates supported	<ol style="list-style-type: none"> 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) IEEE 802.3i 10BASE-T IEEE 802.3u 100BASE-TX IEEE 802.3ab 1000BASE-T IEEE 802.3bz 2.5GBASE-T
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling (Hash Mode Only) Jumbo Frame 9K
	Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bps Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Management Interface	Auto MDI/MDIX Crossover cable detection
	IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Security & Manageability	Intel® non-vPro™ support with appropriate Intel® chipset components

 Technical Specifications

RFID Controller Gen 2 (optional)	Dimensions (L x W x H)	Module 50 mm by 23 mm by 2.89 mm	
	Chipset	SiM3U156+SiM3U154+AMS3911	
	System interface	USB 2.0	
	System interface (I/O)	Audio signal output on card read	
	NFC RF standards (In reading CSN)	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1	
	NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4 in reading CSN	
	Reader Mode	13.56MHz: ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Topaz cards HID iClass ISO 125kHz: HID Prox UID AWID UID CASI-RUSCO UID EM 410x UID Indiana ASP/ASP+ UID	
	Frequency	13.56MHz and 125kHz	
	NFC Modes Supported	Reader	
	Raw RF Data Rates	106, 212 kbps	
	Operating temperature	-30°C to 70°C	
	Storage temperature	-40°C to 80°C	
	Humidity	10-90% operating 5-95% non-operating	
	Supply Operating voltage	4.35 to 5.25 Volts	
	Power Consumption	Mode	Power Consumption, Typical
		Polling	75mA
		Comunication	85mA
	Antenna	13.56MHz/125kHz combo antenna. Antenna connector, 0.5mm pitch, 16pin connector FPC.	

Technical Specifications

POWER

AC Adapter 45 Watt nPFC Standard USB Type-C® Straight 1.8m	Dimensions (H x W x D)	94.0 x 40.0 x 26.5 mm
	Weight	192.5g +/-10%
	Input	Input Efficiency Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%
		Input frequency range 47 ~ 63 Hz
		Input AC current Max. 1.4 A at 90 Vac
	Output	Output power 5V/15W 9V/27W 12V/36W 15V/45W
		DC output 5V/9V/12V/15V
		Hold-up time 5 ms at 115 Vac input
	Connector	USB Type-C®
	Environmental Design	Operating temperature 32°F to 95°F (0° to 35°C) Non-operating (storage) temperature -4°F to 185°F (-20° to 85°C) Altitude 0 to 16,400 ft (0 to 5,000 m) Humidity 20% to 95% Storage Humidity 10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5mm Right Angle 1.8m	Dimensions	95 x 45 x 26.8 mm
	Weight	200 g +/- 10 g
	Input	Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range 47 ~ 63 Hz
		Input AC current Max. 1.4 A at 90 Vac
	Output	Output power 45 W
		DC output 19.5 V
		Hold-up time 5 ms at 115 Vac input
	Output current limit <8.0A	



Technical Specifications

Connector	4.5mm Barrel Type
Environmental Design	Operating temperature 32°F to 95°F (0°to 35°C) Non-operating (storage) temperature -4°F to 185°F (-20°to 85°C) Altitude 0 to 16,400 ft (0 to 5000m) Humidity 20% to 95% Storage Humidity 10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5mm Right Angle 1.8m 2prong	Dimensions	95 x 45 x 26.8 mm	
	Weight	200 g +/- 10 g	
	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 VAC
	Output	Output power	45 W
		DC output	19.5 V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<8.0A
	Connector	4.5mm Barrel Type	
Environmental Design	Operating temperature 32°F to 95°F (0°to 35°C) Non-operating (storage) temperature -4°F to 185°F (-20°to 85°C) Altitude 0 to 16,400 ft (0 to 5000m) Humidity 20% to 95% Storage Humidity 10% to 95%		
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		

AC Adapter 65 Watt nPFC Standard USB type C® Straight 1.8m	Dimensions	90.0 x 51 x 28.5mm
	Weight	250 g +/- 10 g
	Input	Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A



Technical Specifications

		89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
Output	Input frequency range	47 ~ 63 Hz
	Input AC current	1.6 A at 90 VAC and maximum load
	Output power	65 W
	DC output	5V/9V/12V/15V/20V
	Hold-up time	5 ms at 115 Vac input
	Output current limit	8.0A Max.
Connector	USB Type C®	
Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 65 Watt Smart nPFC EM Barrel 4.5mm New EM	Dimensions (H x W x D)	102 x 55 x 30mm	
	Weight	250g +/-10%	
Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac	
	Input frequency range	47 ~ 63 Hz	
	Input AC current	Max. 1.7 A at 90 Vac	
	Output	Output power	65W
Output	DC output	19.5V	
	Hold-up time	5 ms at 115 Vac input	
	Output current limit	<11.0A	
	Connector	4.5mm Barrel Type	
Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)	
	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)	
	Altitude	0 to 16,400 ft (0 to 5,000 m)	
	Humidity	20% to 95%	
	Storage Humidity	10% to 95%	



Technical Specifications

EMI and Safety Certifications

CE Mark - full compliance with LVD and EMC directives
 Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.
 MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt Smart nPFC Standard Barrel 4.5mm Right Angle 1.8m

Dimensions (H x W x D)

90 x 51 x 28.5mm

Weight

230g +/-10%

Input

Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230 Vac
Input frequency range 47 ~ 63 Hz
Input AC current Max. 1.7 A at 90 Vac

Output

Output power 65W
DC output 19.5V
Hold-up time 5 ms at 115 Vac input
Output current limit <11.0A

Connector

4.5mm Barrel Type

Environmental Design

Operating temperature 32°F to 95°F (0° to 35°C)
Non-operating (storage) temperature -4°F to 185°F (-20° to 85°C)
Altitude 0 to 16,400 ft (0 to 5,000 m)
Humidity 20% to 95%
Storage Humidity 10% to 95%

EMI and Safety Certifications

CE Mark - full compliance with LVD and EMC directives
 Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.
 MTBF - over 200,000 hours at 25°C ambient condition.



Technical Specifications

Battery RH 3 Cell WHr 45 Long Life -PL Fast Charge	Dimensions (H x W x L)	6.2 x 68.7 x 249.6mm
	Weight	190g
	Cells/Type	3cell Lithium-Ion Polymer cell/ 545974
	Voltage	11.4 V
	Amp-hour capacity	3.950Ah
	Watt-hour capacity	45 Wh
	Operating (Charging)	32° to 113° F (0° to 45° C)
	Operating (Discharging)	14° to 122° F (-10° to 60° C)
	Optional Travel Battery Available	No
	Warranty	Based on system offering

ENVIRONMENTAL DATA

- Sustainable Impact Specifications**
- Bulk packaging available
 - Low halogen¹
 - Ocean-Bound Plastic in speaker enclosure²
 - Outside Box and corrugated cushions are 100% sustainably sourced and recyclable³
 - 10% post-consumer recycled plastic⁴

1. External power supplies, WWAN modules, power cords, cables and peripherals excluded.
2. Percentage of ocean-bound plastic contained in each component varies by product
3. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
4. Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.

Country of Origin

China

Options and Accessories (sold separately and availability may vary by country)

Type	Description	Part Number
Cases	HP Business Backpack (up to 17.3")	2SC67AA
	HP Business Slim Top Load (up to 14.1")	2SC65AA
	HP Prelude Pro Recycle Backpack (Montrose)	1X644AA
	HP Prelude Pro Recycle Top Load (Midtown)	1X645AA
	HP Recycled Top Load	5KN29AA
	HP Recycled Backpack	5KN28AA
Docking	HP USB-C Mini Dock	1PM64AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/Audio	3YE87AA
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	3AQ21AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP USB-C Dock G5	5TW10AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Wired Desktop 320MK Mouse & Keyboard	9SR36AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP USB Travel Mouse	G1K28AA
	HP Elite USB-C Hub	4WX89AA
	HP USB-C Travel Hub G2	7PJ38AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	45W Smart Power Adapter 2 prong -4.5mm (Japan only)	L6F60AA
	65W Smart Power Adapter (w/ 4.5mm to 7.5mm DC dongle)	H6Y89AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Slim Power Adapter	3PN48AA
	HP 45W LC USB-C Power Adapter	1MZ01AA
	HP 65W USB-C LC Power Adapter	TBD
	HP Power Bank	N9F71AA
	HP USB-C Notebook Power Bank	3TB55AA



Options and Accessories (sold separately and availability may vary by country)

Storage	HP External USB Optical Drive	F2B56AA
Memory	HP 4GB DDR4 3200 Memory	286H5AA
	HP 8GB DDR4 3200 Memory	286H8AA
	HP 16GB DDR4 3200 Memory	286J1AA
Security	HP Sure Key Cable Lock	6UW42AA
	HP Nano Keyed Cable Lock	1AJ39AA



Summary of Changes

Date of change:	Version History:		Description of change:
January 15, 2021	V1 to V2	Update	Processor section
January 21, 2021	V2 to V3	Added	WPA3 certification in Security, Networking section
February 3, 2021	V3 to V4	Update	Software and Security section
February 9, 2021	V4 to V5	Added	Environmental Data
February 24, 2021	V5 to V6	Update	USB Ports
March 24, 2021	V6 to V7	Update	Processors base frequency
April 19, 2021	V7 to V8	Added	Intel I219-LM(v-Pro)/I219-V (non-vPro)/Memory Modules
April 30, 2021	V8 to V9	Updated	USB Ports/TPM 2.0
May 6, 2021	V9 to V10	Removed	Processors base frequency/Added HP Smart Support

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